

**IN THE CLAIMS:**

Claim 1 (currently amended): A method of peeling a semiconductor chip, comprising the steps of:

peeling a semiconductor chip adhered to a tape from said tape by a peeling device including a plurality of annular displaceable contact members arranged in an order from an outer circumferential position to a central position all being housed inside a stationary contact member ~~arranged one after another from the outside to the inside~~, wherein the plurality of displaceable annular contact members are operated and displaced relative to each other so that the semiconductor chip is successively peeled off from the tape from ~~an~~ the outer circumferential ~~portion~~ position thereof toward a the central ~~portion thereof~~ position.

Claim 2 (original): The method of peeling a semiconductor chip according to claim 1, wherein the plurality of annular contact members are simultaneously moved, and then, the outermost annular contact member in the plurality of annular contact members is stopped and the remaining annular contact members are further moved simultaneously.

Claim 3 (currently amended): A device for peeling a semiconductor chip adhered to a tape off from said tape, comprising:

a plurality of annular displaceable contact members arranged in an order from an outer circumferential position to a central position all being housed inside a stationary

contact member one after another from the outside to the inside; and

an operation device for operating the plurality of displaceable annular contact members to displace them relative to each other so that the semiconductor chip is successively peeled, from the tape, from ~~an~~ the outer circumferential ~~portion~~ position thereof to a the central portion thereof position.

Claim 4 (original): The device for peeling a semiconductor chip according to claim 3, wherein the operation device includes a cam for operating the plurality of annular contact members.

Claim 5 (original): The device for peeling a semiconductor chip according to claim 3, further comprising a frame defining a vacuum chamber therein, a top plate arranged on said frame and having an opening, and a suction device arranged above said frame, said annular contact members being arranged in said frame.

Claim 6 (new): A method of peeling a semiconductor chip, comprising the steps of:

peeling a semiconductor chip adhered to a tape from said tape by a peeling device including a plurality of annular contact members arranged one after another from the outside to the inside, wherein the plurality of annular contact members are operated so that the semiconductor chip is successively peeled off from the tape from an outer circumferential portion thereof toward a central portion thereof; and

wherein the plurality of annular contact members are simultaneously moved, and then, the outermost annular contact member in the plurality of annular contact members is stopped and the remaining annular contact members are further moved simultaneously.